

# PC4SF21YVZ Series

\*Non-zero cross type is also available. (PC4SF11YVZ Series)

V<sub>DRM</sub> : 800V, Reinforced insulation type Zero cross type **DIP 6pin** Phototriac Coupler for triggering



# Description

PC4SF21YVZ Series reinforced insulation type Phototriac Coupler include an infrared emitting diode (IRED) optically coupled to an output Phototriac.

These devices feature full wave control and are ideal isolated drivers for medium to high current Triacs.

DIP package provides 5.0kV isolation from input to output with superior commutative noise immunity.

#### Features

- 1. High repetitive peak off-state voltage (V<sub>DRM</sub> : 800V)
- 2. Zero crossing functionality (V<sub>OX</sub> : MAX. 20V)
- 3. IFT ranks available (see Model Line-up section in this datasheet)
- 4. 6 pin DIP package
- 5. Reinforced insulation type (MIN. 0.4mm internal separation)
- 6. Superior noise immunity (dV/dt : MIN. 500V/µs)
- 7. Lead-free components are also available (see Model Line-up section in this datasheet)
- 8. Double transfer mold construction (Ideal for Flow Soldering)
- 9. High isolation voltage between input and output  $(V_{iso}(rms) : 5.0kV)$

#### Agency approvals/Compliance

- 1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. 4SF21)
- 2. Approved by CSA, file No. CA95323 (as model No. 4SF21)
- 3. Approved by BSI : BS-EN60065, file No. 6690/BS-EN60950, file No. 7421, (as model No. 4SF21)
- 4. Approved by SEMKO, EN60065/EN60950, file No. 0033029 (as model No. 4SF21)
- 5. Approved by DEMKO, EN60065/EN60950, file No. 310107 (as model No. 4SF21)
- 6. Approved by FIMKO, EN60065/EN60950, file No. 15795 (as model No. 4SF21)
- 7. Approved by VDE (\*)(DIN EN 60747-5-2), file No. 40008189 (as model No. 4SF21)
- 8. Package resin : UL flammability grade (94V-0)

(\*) DIN EN60747-5-2 : successor standard of DIN VDE0884 Up to Date code "RD" (December 2003), approval of DIN VDE0884. From Date code "S1" (January 2004), approval of DIN EN60747-5-2.

#### Applications

1. Triggering for Triacs used to switch on and off devices which require AC Loads.

For example heaters, fans, motors, solenoids, and valves.

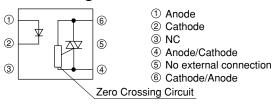
2. AC line control in power supply applications.

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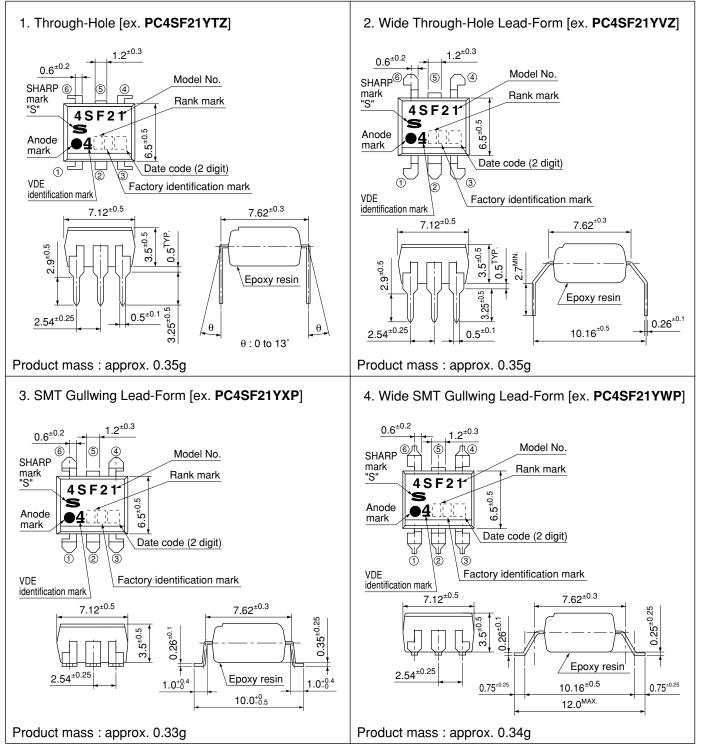


#### Internal Connection Diagram



### Outline Dimensions

(Unit : mm)



\*Pin 5 is not allowed external connection



# Date code (2 digit)

			ì		
1st o	ligit		2nd digit		
Year of p	roduction		Month of production		
Mark	A.D	Mark	Month	Mark	
А	2002	Р	January	1	
В	2003	R	February	2	
С	2004	S	March	3	
D	2005	Т	April	4	
Е	2006	U	May	5	
F	2007	V	June	6	
Н	2008	W	July	7	
J	2009	Х	August	8	
K	2010	А	September	9	
L	2011	В	October	0	
М	2012	С	November	N	
Ν	:	:	December	D	
	Year of p Mark A B C D E F H J K J K L M	A         2002           B         2003           C         2004           D         2005           E         2006           F         2007           H         2008           J         2009           K         2010           L         2011           M         2012	Year of production           Mark         A.D         Mark           A         2002         P           B         2003         R           C         2004         S           D         2005         T           E         2006         U           F         2007         V           H         2008         W           J         2009         X           K         2010         A           L         2011         B           M         2012         C	Year of productionMonth ofMarkA.DMarkMonthA2002PJanuaryB2003RFebruaryC2004SMarchD2005TAprilE2006UMayF2007VJuneH2008WJulyJ2009XAugustK2010ASeptemberL2011BOctoberM2012CNovember	

repeats in a 20 year cycle

# Factory identification mark

Factory identification Mark	Country of origin
no mark	I
	Japan
	Indonesia
$\overline{\nabla}$	Philippines
	China

\* This factory marking is for identification purpose only.

Please contact the local SHARP sales representative to see the actural status of the production.

### Rank mark

Refer to the Model Line-up table

#### Absolute Maximum Ratings

Abs	■ Absolute Maximum Ratings (T <sub>a</sub> =2:						
	Parameter	Symbol	Rating	Unit			
Innut	Forward current	I <sub>F</sub>	50	mA			
Input	Reverse voltage	VR	6	V			
	RMS ON-state current	I <sub>T</sub> (rms)	0.1	Α			
Output	Peak one cycle surge current	I <sub>surge</sub>	1.2 *3	Α			
	Repetitive peak OFF-state voltage	V <sub>DRM</sub>	800	V			
<sup>*1</sup> Isolatio	on voltage	V <sub>iso</sub> (rms)	5.0	kV			
	ing temperature	T <sub>opr</sub>	-30 to +100	°C			
Storag	e temperature	T <sub>stg</sub>	-55 to +125	°C			
*2 Solder	ing temperature	T <sub>sol</sub>	270 *4	°C			

\*1 40 to 60%RH, AC for 1minute, f=60Hz \*2 For 10s \*3 f=50Hz sine wave

\*4 Lead solder plating models: 260°C

# ■ Electro-optical Characteristics

1 mm Soldering area

 $(T_a=25^{\circ}C)$ 

	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
T	Forward voltage		V <sub>F</sub>	I <sub>F</sub> =20mA	-	1.2	1.4	V
Input	Reverse current		I <sub>R</sub>	V <sub>R</sub> =3V	-	_	10	μΑ
	Repentitive peak OFF-state	current	I <sub>DRM</sub>	V <sub>D</sub> =V <sub>DRM</sub>	-	_	3	μΑ
	ON-state voltage		VT	I <sub>T</sub> =0.1A	_	_	2.5	V
Orteret	Holding current		I <sub>H</sub>	V <sub>D</sub> =4V	0.1	_	3.5	mA
Output	Critical rate of rise of OFF-state voltage		dV/dt	$V_{D}=1/\sqrt{2} \cdot V_{DRM}$	500	1 000	-	V/µs
	Zara araga valtaga	Rank B	Vox	I <sub>F</sub> =15mA, Resistance load			20	v
	Zero cross voltage	Rank C	• OX	I <sub>F</sub> =8mA, Resistance load		_	20	
	Minimum trigger europt	Rank B	I <sub>FT</sub>	$V_{\rm D}=4V, R_{\rm I}=100\Omega$	-	-	7	
Transfer	Minimum trigger current	Rank C	1 <sub>FT</sub>	$v_{\rm D}=4v,  n_{\rm L}=10022$	-	-	5	mA
charac- teristics	Isolation resistance		R <sub>ISO</sub>	DC500V,40 to 60%RH	5×10 <sup>10</sup>	1011	-	Ω
	Turn-on time		t <sub>on</sub>	$V_D=4V, R_L=100\Omega, I_F=20mA$	_	_	50	μs



# ■ Model Line-up (1) (Lead-free components)

Lead Form	Through-Hole SMT Gullwing Wide Through-Hole								
				Rank mark	$I_{FT}[mA]$ (V <sub>D</sub> =4V,				
Shipping Package									
DIN EN60747-5-2		Approved		Approved		Approved		$R_L=100\Omega$ )	
Model No.		PC4SF21YTZBF		PC4SF21YXZBF		PC4SF21YVZBF	В	MAX.7	
Wodel No.		PC4SF21YTZCF		PC4SF21YXZCF		PC4SF21YVZCF	С	MAX.5	

Lead Form	Wide SMT Gullwing		SMT Gullwing Wide SMT		Γ Gullwing				
Chinaine Declares	Sleeve			Taj			I <sub>FT</sub> [mA]		
Shipping Package	50pcs/sleeve		1 000pcs/reel				Rank mark	$(V_D=4V,$	
DIN EN60747-5-2		Approved		Approved		Approved		$R_L=100\Omega$ )	
Model No.		PC4SF21YWZBF		PC4SF21YXPBF		PC4SF21YWPBF	В	MAX.7	
Widdel No.		PC4SF21YWZCF		PC4SF21YXPCF		PC4SF21YWPCF	С	MAX.5	

# ■ Model Line-up (2) (Lead solder plating components)

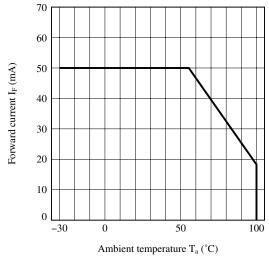
Lead Form	Through-Hole SMT Gullwing Wide Through-Hole					ough-Hole			
01 D 1				Rank mark	$I_{FT}[mA]$ (V <sub>D</sub> =4V,				
Shipping Package									
DIN		Approved		Approved		Approved		$R_L=100\Omega$ )	
EN60747-5-2		Appioved		Approved		Appioved			
Model No.		PC4SF21YTZB		PC4SF21YXZB		PC4SF21YVZB	В	MAX.7	
would no.		PC4SF21YTZC		PC4SF21YXZC		PC4SF21YVZC	С	MAX.5	

Lead Form	Wide SMT Gullwing		SMT Gullwing Wide SMT		Γ Gullwing			
	Sleeve		Taping				Rank mark	I <sub>FT</sub> [mA]
Shipping Package	50pcs/sleeve		1 000pcs/reel					$(V_D=4V,$
DIN EN60747-5-2		Approved		Approved		Approved		$R_L=100\Omega)$
Model No.		PC4SF21YWZB		PC4SF21YXPB		PC4SF21YWPB	В	MAX.7
Widdel No.		PC4SF21YWZC		PC4SF21YXPC		PC4SF21YWPC	С	MAX.5

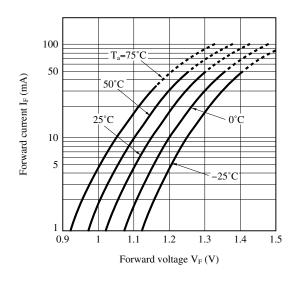
Please contact a local SHARP sales representative to inquire about production status.



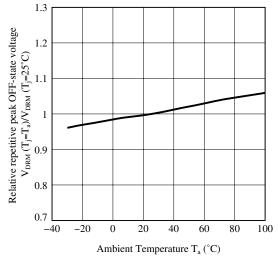




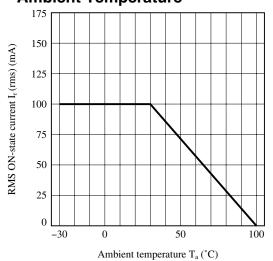
### Fig.3 Forward Current vs. Forward Voltage



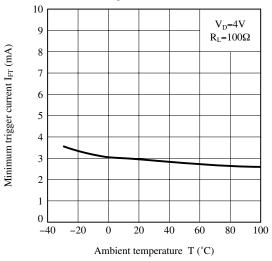




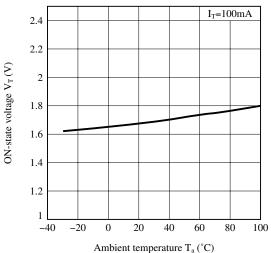
#### Fig.2 RMS ON-state Current vs. Ambient Temperature



# Fig.4 Minimum Trigger Current vs. Ambient Temperature

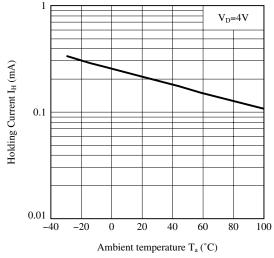


# Fig.6 ON-state Voltage vs. Ambient Temperature

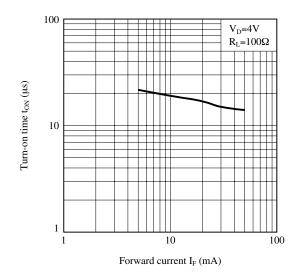


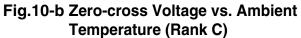


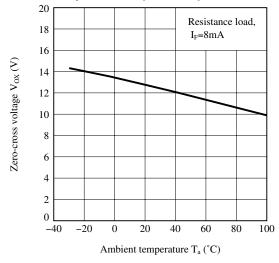
# Fig.7 Holding Current vs. Ambient Temperature



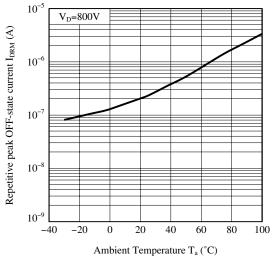
# Fig.9 Turn-on Time vs. Forward Current



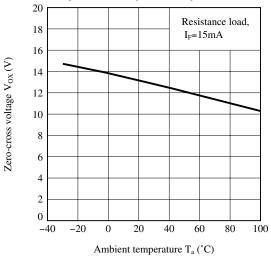




# Fig.8 Repetitive Peak OFF-state Current vs. Ambient Temperature



# Fig.10-a Zero-cross Voltage vs. Ambient Temperature (Rank B)



Remarks : Please be aware that all data in the graph are just for reference.



#### Design Considerations

#### Design guide

In order for the Phototriac to turn off, the triggering current ( $I_F$ ) must be 0.1mA or less.

Please refrain from using these devices in a direct drive configuration. These Phototriac Coupler are intended to be used as triggering device for main Triacs. Please ensure that the output rating of these devices will be sufficient for triggering the main output Triac of your choice. Failure to do may result in malfunctions.

For applications with inductive loads such as motors, please use caution in utilizing a zero crossing type Phototraiac Coupler as this may cause undesired operations due to the phase difference between voltage and current of load.

For designs that will experience excessive noise or sudden changes in load voltage, please include an appropriate snubber circuit as shown in the below circuit. Please keep in mind the Sharp Phototriac Coupler incorporate superrior dV/dt ratings which can eliminate the need for a snubber circuit.

For over voltage protection, a Varistor may be used.

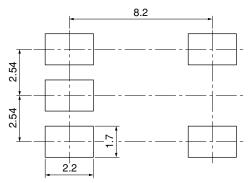
#### Degradation

In general, the emission of the IRED used in Phototriac Couplers will degrade over time. In the case where long term operation and / or constant extreme temperature fluctuations will be applied to the devices, please allow for a worst case scenario of 50% degradation over 5years.

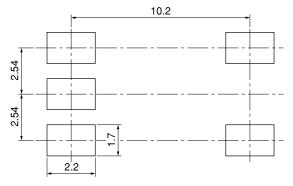
Therefore in order to maintain proper operation, a design implementing these Phototriac Couplers should provide at least twice the minimum required triggering current from initial operation.

#### • Recommended Foot Print (reference)

SMT Gullwing Lead-form



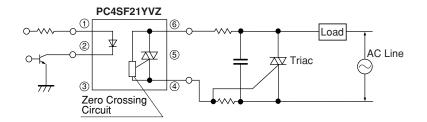
#### Wide SMT Gullwing Lead-form



(Unit : mm)



#### • Standard Circuit (Medium/High Power Triac Drive Circuit)



Note) Please add the snubber circuit according to a condition. Any snubber or varistor used for the above mentioned scenarios should be located as close to the main output triac as possible.

☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

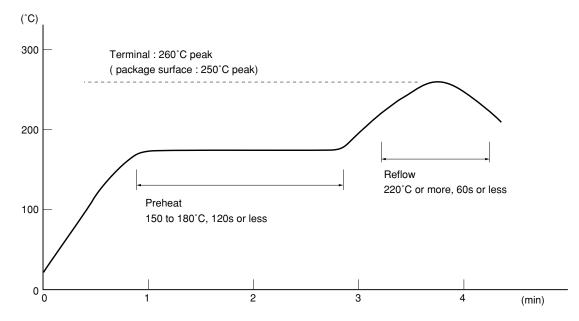


#### Manufacturing Guidelines

#### Soldering Method

**Reflow Soldering:** 

Reflow soldering should follow the temperature profile shown below. Soldering should not exceed the curve of temperature profile and time. Please don't solder more than twice.



#### Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 270°C and within 10s. Preheating is within the bounds of 100 to 150°C and 30 to 80s. Please don't solder more than twice.

#### Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C. Please don't solder more than twice.

#### Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



#### • Cleaning instructions

Solvent cleaning :

Solvent temperature should be 45°C or below. Immersion time should be 3minutes or less.

#### Ultrasonic cleaning :

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

#### Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

#### Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform) Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.



#### Package specification

#### • Sleeve package

#### 1. Through-Hole or SMT Gullwing

Package materials

Sleeve : HIPS (with anti-static material) Stopper : Styrene-Elastomer

#### Package method

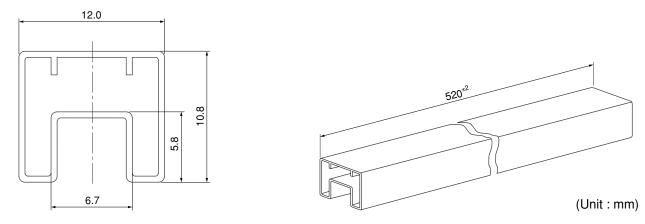
MAX. 50pcs of products shall be packaged in a sleeve.

Both ends shall be closed by tabbed and tabless stoppers.

The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.

MAX. 20 sleeves in one case.

#### Sleeve outline dimensions



# 2. Wide Through-Hole or Wide SMT Gullwing

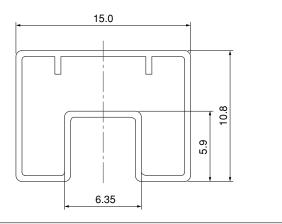
Package materials

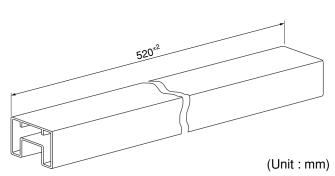
Sleeve : HIPS (with anti-static material) Stopper : Styrene-Elastomer

#### Package method

MAX. 50pcs of products shall be packaged in a sleeve.Both ends shall be closed by tabbed and tabless stoppers.The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.MAX. 20 sleeves in one case.

#### Sleeve outline dimensions





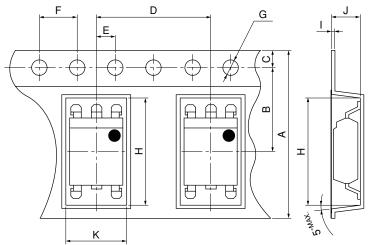


• Tape and Reel package

# 1. SMT Gullwing

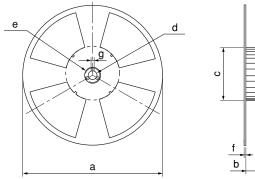
Package materials Carrier tape : A-PET (with anti-static material) Cover tape : PET (three layer system) Reel : PS

Carrier tape structure and Dimensions



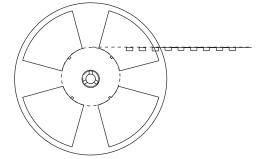
Dimensio	Dimensions List									
А	В	С	D	Е	F	G				
16.0 <sup>±0.3</sup>	$7.5^{\pm 0.1}$	$1.75^{\pm 0.1}$	$12.0^{\pm0.1}$	$2.0^{\pm 0.1}$	$4.0^{\pm 0.1}$	φ1.5 <sup>+0.1</sup>				
Н	Ι	J	K							
$10.4^{\pm 0.1}$	$0.4^{\pm 0.05}$	$4.2^{\pm 0.1}$	$7.8^{\pm 0.1}$							

Reel structure and Dimensions

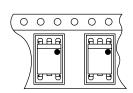


Dimensio	ns List	(Unit : mm)			
а	b	с	d		
330	$17.5^{\pm 1.5}$	100 <sup>±1.0</sup>	13 <sup>±0.5</sup>		
e	f	g			
23 <sup>±1.0</sup>	$2.0^{\pm 0.5}$	$2.0^{\pm 0.5}$			

# Direction of product insertion



Pull-out direction



[Packing : 1 000pcs/reel]

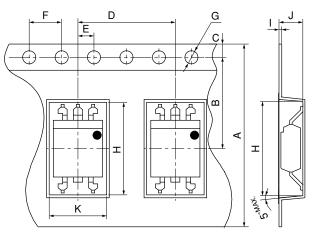


# 2. Wide SMT Gullwing

Package materials

Carrier tape : A-PET (with anti-static material) Cover tape : PET (three layer system) Reel : PS

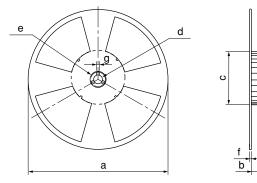
Carrier tape structure and Dimensions



1 Init	mm)
Unit	mm)

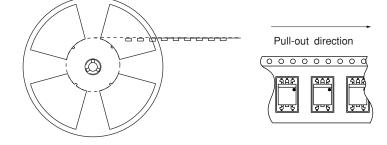
Dimensior	Dimensions List (Un								
А	В	C	D	Е	F	G			
24.0 <sup>±0.3</sup>	$11.5^{\pm 0.1}$	$1.75^{\pm 0.1}$	$12.0^{\pm0.1}$	$2.0^{\pm 0.1}$	$4.0^{\pm 0.1}$	φ1.5 <sup>+0.1</sup>			
Н	Ι	J	K						
$12.2^{\pm 0.1}$	$0.4^{\pm 0.05}$	$4.15^{\pm0.1}$	$7.6^{\pm 0.1}$						

Reel structure and Dimensions



Dimensions List		(Unit : mm)	
a	b	с	d
330	$25.5^{\pm 1.5}$	$100^{\pm 1.0}$	13 <sup>±0.5</sup>
e	f	g	
23 <sup>±1.0</sup>	$2.0^{\pm 0.5}$	2.0 <sup>±0.5</sup>	

Direction of product insertion



[Packing: 1 000pcs/reel]

# SHARP

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- --- Personal computers
- --- Office automation equipment
- --- Telecommunication equipment [terminal]
- --- Test and measurement equipment
- --- Industrial control
- --- Audio visual equipment
- --- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- --- Space applications
- --- Telecommunication equipment [trunk lines]
- --- Nuclear power control equipment
- --- Medical and other life support equipment (e.g., scuba).

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